

FAST CMOS BUFFER/CLOCK DRIVER

FEATURES:

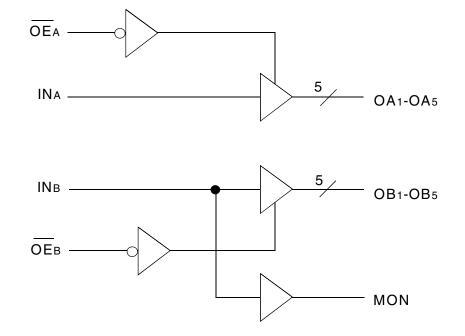
- 0.5 MICRON CMOS Technology
- Guaranteed low skew < 500ps (max.)
- Very low duty cycle distortion < 600ps (max.)
- · Low CMOS power levels
- TTL compatible inputs and outputs
- · TTL level output voltage swings
- High drive: -32mA Іон, +48mA Іоь
- · Two independent output banks with 3-state control
- 1:5 fanout per bank
- · "Heartbeat" monitor output
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- Available in the following packages:
 - Commercial: QSOP, SOIC, SSOP
 - Military: CERDIP, LCC

DESCRIPTION:

This buffer/clock driver is built using advanced dual metal CMOS technology. The FCT805T is a non-inverting clock driver consisting of two banks of drivers. Each bank drives five output buffers from a standard TTL compatible input. This part has extremely low output skew, pulse skew, and package skew. The device has a "heart-beat" monitor for diagnostics and PLL driving. The monitor output is identical to all other outputs and complies with the output specifications in this document.

The FCT805T is designed for fast, clean edge rates to provide accurate clock distribution in high speed systems.

FUNCTIONAL BLOCK DIAGRAM

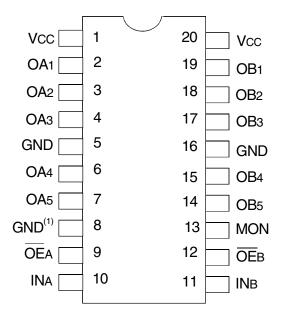


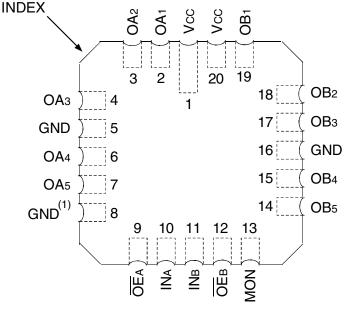
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MILITARY AND COMMERCIAL TEMPERATURE RANGES

MAY 2010

PIN CONFIGURATION





LCC TOP VIEW

QSOP/ SOIC/ SSOP/ CERDIP TOP VIEW

NOTE:

1. Pin 8 is internally connected to GND. To insure compatibility with all products, pin 8 should be connected to GND at the board level.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Description	Max	Unit
VTERM	Terminal Voltage with Respect to GND	–0.5 to +7	V
Tstg	StorageTemperature	–65 to +150	°C
Ιουτ	DC Output Current	-60 to +120	mA
NOTE			

NOTE:

 Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

CAPACITANCE (TA = +25°C, f = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Тур.	Max.	Unit
CIN	Input Capacitance	VIN = 0V	4.5	6	pF
Соит	Output Capacitance	Vout = 0V	5.5	8	pF

NOTE:

1. This parameter is measured at characterization but not tested.

PINDESCRIPTION

Pin Names	Description	
ΟΕΑ, ΟΕΒ	3-State Output Enable Inputs (Active LOW)	
INA, INB	Clock Inputs	
OAx, OBx	Clock Outputs	
MON Monitor Output		

FUNCTION TABLE (1)

Inpu	uts	Outputs		
OEA, OEB	INA, INB	OAx, OBx	MON	
L	L	L	L	
L	Н	Н	Н	
Н	L	Z	L	
Н	Н	Z	Н	

NOTE: 1. H = HIGH

L = LOW

Z = High-Impedance

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Commercial: TA = 0°C to +70°C, Military: TA = -55°C to +125°C, Vcc = 5V \pm 10%

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Тур. ⁽²⁾	Max.	Unit
Vih	Input HIGH Level	Guaranteed Logic HI	Guaranteed Logic HIGH Level		-	—	V
Vil	Input LOW Level	Guaranteed Logic LC)W Level	-	_	0.8	V
Ін	Input HIGH Current ⁽⁵⁾	Vcc = Max.	VI = 2.7V	-	-	±1	μA
lil	Input LOW Current ⁽⁵⁾	Vcc = Max.	VI = 0.5V	-	—	±1	μA
lozн	High Impedance Output Current	Vcc = Max.	Vo = 2.7V	_	—	±1	μA
Iozl	(3-State Output Pins)		Vo = 0.5V	-	_	±1	
li	Input HIGH Current	Vcc = Max., VI = Vc	cc (Max.)	_	—	±1	μA
Vik	Clamp Diode Voltage	Vcc = Min., IIN = -18	3mA	_	-0.7	-1.2	V
los	Short Circuit Current	Vcc = Max., Vo = G	Vcc = Max., Vo = GND ⁽³⁾		-120	-255	mA
		Vcc = Min.	Iон = –12mA MIL	2.4	3.3	_	V
Vон	Output HIGH Voltage	VIN = VIH or VIL	Іон = –15mA COM'L				
			Iон = -24mA MIL	2	3	_	V
			$IOH = -32mA COM'L^{(4)}$				
Vol	Output LOW Voltage	Vcc = Min.	Iol = 32mA MIL	-	0.3	0.55	V
		VIN = VIH or VIL	Iol = 48mA COM'L				
loff	Input/Output Power Off Leakage ⁽⁵⁾	VCC = 0V, VIN or VC	Vcc = 0V, Vin or Vo ≤4.5V		-	±1	μA
Vн	Input Hysteresis for all inputs	-		-	150	_	mV
ICCL	Quiescent Power Supply Current	Vcc = Max., VIN = GND or Vcc		_	5	500	μA
Іссн							
Iccz							

NOTES:

1. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.

2. Typical values are at Vcc = 5V, +25°C ambient.

3. Not more than one output should be shorted at one time. Duration of the test should not exceed one second.

4. Duration of the condition should not exceed one second.

5. The test limit for this parameter is $\pm 5\mu A$ at TA = -55°C.

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Cond	ditions ⁽¹⁾	Min.	Typ. ⁽²⁾	Max.	Unit
ΔΙCC	Quiescent Power Supply Current	Vcc = Max.		-	1	2	mA
	TTL Inputs HIGH	$VIN = 3.4V^{(3)}$					
ICCD	Dynamic Power Supply Current ⁽⁴⁾	Vcc = Max.	VIN = VCC	-	60	100	µA/MHz
		Outputs Open	VIN = GND				
		OEA = OEB = GND					
		50% Duty Cycle					
Ic	Total Power Supply Current ⁽⁶⁾	Vcc = Max.	VIN = VCC	-	1.5	3	
		Outputs Open	VIN = GND				
		fo = 25MHz					
		50% Duty Cycle	VIN = 3.4V	-	1.8	4	
		OEA = OEB = VCC	VIN = GND				
		Mon. Output Toggling					
		Vcc = Max.	VIN = VCC	_	33	55.5 ⁽⁵⁾	mA
		Outputs Open	VIN = GND				
		fo = 50MHz					
		50% Duty Cycle	VIN = 3.4V	_	33.5	57.5 ⁽⁵⁾]
		OEA = OEB = GND	VIN = GND				
		Eleven Outputs Toggling					

NOTES:

1. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.

- 2. Typical values are at Vcc = 5V, +25°C ambient.
- 3. Per TTL driven input (VIN = 3.4V); all other inputs at Vcc or GND.
- 4. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
- 5. Values for these conditions are examples of the Ic formula. These limits are guaranteed but not tested.
- 6. IC = IQUIESCENT + INPUTS + IDYNAMIC
 - IC = ICC + Δ ICC DHNT + ICCD (foNo)
 - Icc = Quiescent Current (IccL, IccH and Iccz)
 - Δ Icc = Power Supply Current for a TTL High Input (VIN = 3.4V)
 - DH = Duty Cycle for TTL Inputs High
 - NT = Number of TTL Inputs at DH
 - ICCD = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)
 - fo = Output Frequency
 - No = Number of Outputs at fo
 - All currents are in milliamps and all frequencies are in megahertz.

SWITCHING CHARACTERISTICS OVER OPERATING RANGE - MILITARY^(1,2)

			FCT8	05BT	FCT8	05CT	
Symbol	Parameter	Conditions ⁽³⁾	Min. ⁽⁴⁾	Max.	Min. ⁽⁴⁾	Max.	Unit
t PLH	Propagation Delay	CL = 50pF	1.5	5.7	1.5	5.2	ns
t PHL	INA to OAx, INB to OBx	$RL = 500\Omega$					
₽	Output Rise Time		_	2	—	2	ns
tF	OutputFallTime		—	1.5	—	1.5	ns
tsk(0)	Output skew: skew between outputs of all banks of		—	0.9	—	0.7	ns
	same package (inputs tied together)						
tsk(P)	Pulse skew: skew between opposite transitions		—	0.9	—	0.8	ns
	of same output (tphl tpLH)						
tsk(PP)	Part-to-part skew: skew between outputs of different		_	1.5	_	1.2	ns
	packages at same power supply voltage,						
	temperature, package type and speed grade						
tPZL	Output Enable Time		1.5	6.5	1.5	6	ns
tpzh	OEA to OAx, OEB to OBx						
tPLZ	Output Disable Time		1.5	6.5	1.5	6	ns
t PHZ	OEA to OAx, OEB to OBx						

NOTES:

1. tPLH, tPHL, and tsk(pp) are production tested. All other parameters are guaranteed but not production tested.

2. Propagation delay range indicated by Min. and Max. limit is dues to Vcc, operating temperature, and process parameters. These propagation delay limits do not imply skew.

3. See Test Circuits and Waveforms.

4. Minimum limits are guaranteed but not tested on Propagation Delays.

SWITCHING CHARACTERISTICS OVER OPERATING RANGE - COMMERCIAL^(1,2)

			FCT8	05BT	FCT8	05CT	
Symbol	Parameter	Conditions ⁽³⁾	Min. ⁽⁴⁾	Max.	Min. ⁽⁴⁾	Max.	Unit
t PLH	Propagation Delay	CL = 50pF	1.5	5	1.5	4.5	ns
t PHL	INA to OAx, INB to OBx	$RL = 500\Omega$					
tR	Output Rise Time		_	1.5	—	1.5	ns
tF	Output Fall Time		_	1.5	—	1.5	ns
tsk(0)	Output skew: skew between outputs of all banks of same package (inputs tied together)		—	0.7	_	0.5	ns
tsk(P)	Pulse skew: skew between opposite transitions of same output (tPHL tPLH)		—	0.7	_	0.6	ns
tsk(pp)	Part-to-part skew: skew between outputs of different packages at same power supply voltage, temperature, package type and speed grade		_	1.2	_	1	ns
tPZL	Output Enable Time		1.5	6	1.5	5	ns
t PZH	OEA to OAx, OEB to OBx						
tplz	Output Disable Time		1.5	6	1.5	5	ns
t PHZ	OEA to OAx, OEB to OBx						

NOTES:

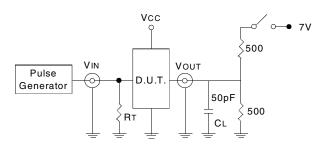
1. tPLH, tPHL, and tsk(pp) are production tested. All other parameters are guaranteed but not production tested.

2. Propagation delay range indicated by Min. and Max. limit is dues to Vcc, operating temperature, and process parameters. These propagation delay limits do not imply skew.

3. See Test Circuits and Waveforms.

4. Minimum limits are guaranteed but not tested on Propagation Delays.

TEST CIRCUITS AND WAVEFORMS



Test Circuits for All Outputs

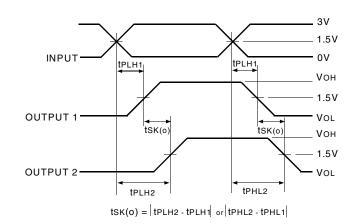


Test	Switch
Disable LOW Enable LOW	Closed
Disable HIGH Enable HIGH	GND

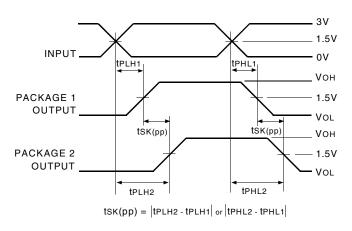
DEFINITIONS:

CL = Load capacitance: includes jig and probe capacitance.

RT = Termination resistance: should be equal to ZOUT of the Pulse Generator.



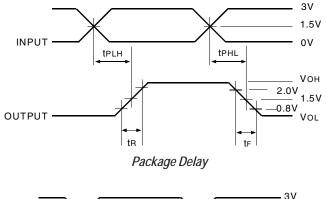


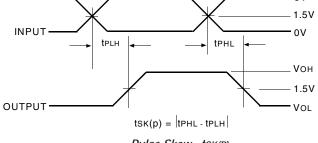


Part-to-Part Skew - tsk(PP)

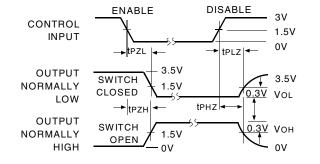
NOTE:

1. Package 1 and Package 2 are same device type and speed grade.







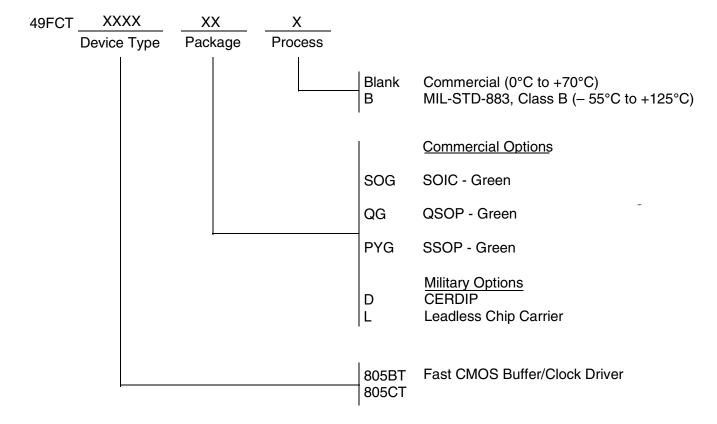


Enable and Disable Times

NOTES:

1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH 2. Pulse Generator for All Pulses: Rate \leq 1.0MHz; tr \leq 2.5ns; tr \leq 2.5ns

ORDERING INFORMATION



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TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan www.renesas.com

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